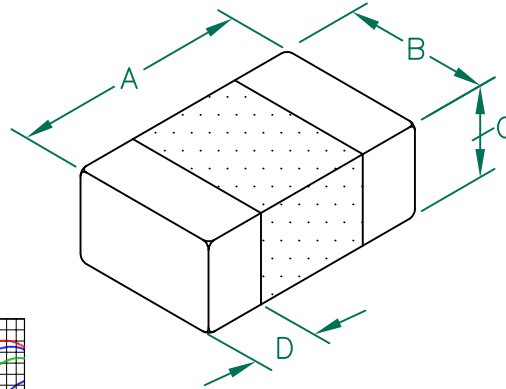


# LI0805H750R-10

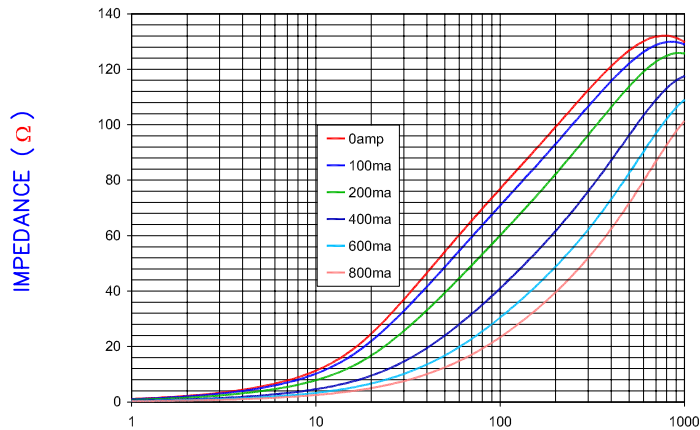
**UNCONTROLLED  
DOCUMENT**

## PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]

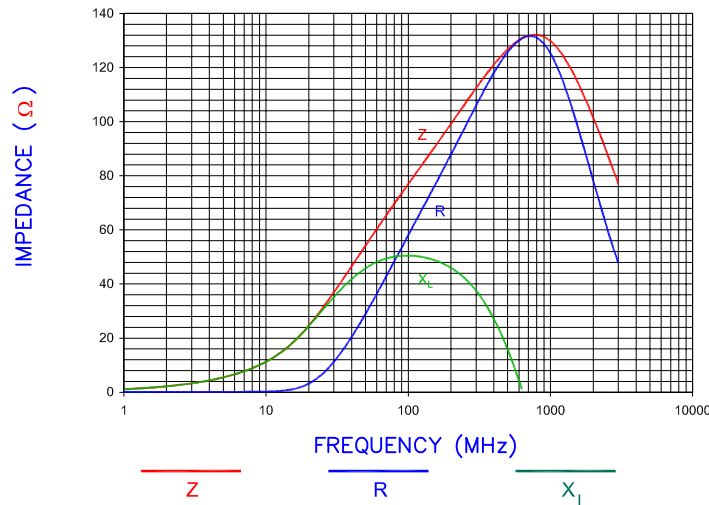


Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



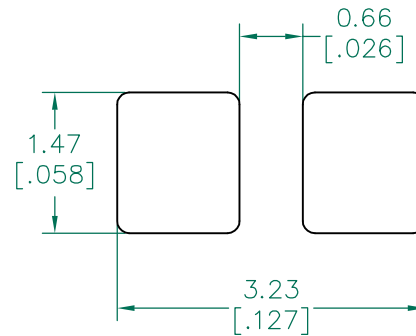
FREQUENCY (MHz)

|Z|, R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer  
HP 16194A Test Fixture. TEST REF. 3235

## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

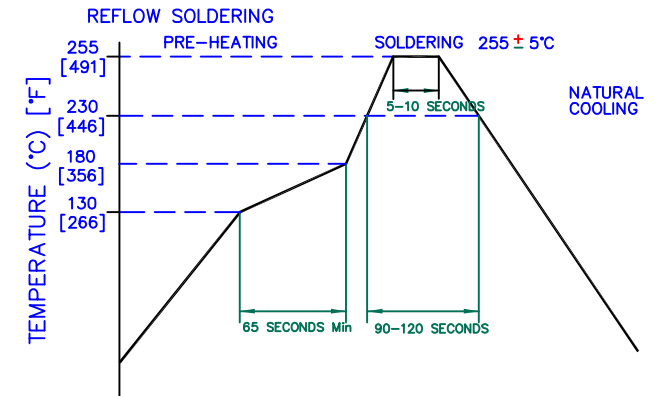
## ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	75	
Minimum	56	
Maximum	94	800 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

## RECOMMENDED SOLDERING CONDITIONS



**RoHS**  
2002/95/EC

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
D	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	<div>PROJECT/PART NUMBER: <b>LI0805H750R-10</b></div> <div>REV <b>D</b> PART TYPE: <b>CO-FIRE</b> DRAWN BY: <b>TMB</b></div> <div>DATE: <b>04/05/04</b> SCALE: <b>NTS</b> SHEET: <b>2 of 2</b></div> <div>CAD # <b>LI0805H750R-10-D</b> TOOL # <b>-</b></div>			
C	CHANGE TO PAPER TAPE	03/04/10	JUN				
B	UPDATE COMPANY LOGO ADD ROHS SYM	07/21/08	JRK				
A	ORIGINAL DRAFT	04/05/04	TMB				
REV	DESCRIPTION	DATE	INT				

**Laird**